Materials Declaration

Package	LFCSP
Body Size	4 X 4
LeadCount	16
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	84.0	3.03 E-02	484324
Multiaromatic Resin	16.0	5.78 E-03	92252

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.21 E-02	193069
Ni	3.0	3.77 E-04	6021
Si	0.65	8.17 E-05	1305
Mg	0.15	1.89 E-05	301

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	4.00 E-05	639

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	2.50 E-04	3996

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.9	2.38 E-04	3806

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	8.89 E-03	141856

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	70.0	3.18 E-03	50703
Resin	21.0	9.53 E-04	15211
Metal Oxide	3.0	1.36 E-04	2173
Amine	3.0	1.36 E-04	2173
Gamma Butyrolactone	3.0	1.36 E-04	2173

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA 3052
Cd	Not Detected	US EPA 3052
Hg	Not Detected	US EPA 3052
Cr+6	Not Detected	US EPA 3060A & 7196A
PBB	Not Detected	Analysis performed by GC/MS
PBDE	Not Detected	Analysis performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	US EPA 3052
Cd	Not Detected	US EPA 3052
Hg	Not Detected	US EPA 3052
Cr+6	Not Detected	US EPA 3060A & 7196A
PBB	Not Detected	Analysis performed by GC/MS
PBDE	Not Detected	Analysis performed by GC/MS

Package Totals

Weight (g)	PPM
6.26 E-02	1000000

AMK-CP-C

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES